

AMENDMENTS TO THE CLAIMS

Please amend claims 7 and 8, to read as follows:

1. (Original) An installation structure of an electronic component for a tire, where the electronic component housed in a case is installed at an arbitrary installation position in an air chamber of the tire, characterized in that a heat-insulating structure is interposed between the electronic component and the installation position.

2. (Original) An installation structure of an electronic component for a tire, where an electronic component housed in a case is installed at an arbitrary installation position in an air chamber of the tire, characterized in that a heat-insulating structure is interposed between the case and the installation position.

3. (Original) An installation structure of an electronic component for a tire, where an electronic component housed in a case is installed at an arbitrary installation position in an air chamber of the tire, characterized in:

that a pedestal including a base plate part which comes into contact with the installation position, and supporting parts which support the case is used;

that the base plate part of the pedestal is attached to the installation position;

that the case is fixed to the supporting parts of the pedestal; and

that a heat-insulating structure is interposed between the case and the base plate part of the pedestal.

4. (Original) The installation structure of an electronic component for a tire according to any of claims 1 to 3, wherein a heat-insulating space is interposed as the heat-insulating structure.

5. (Original) The installation structure of an electronic component for a tire according to any of claims 1 to 3, wherein a heat-insulating material is interposed as the heat-insulating structure.

6. (Original) The installation structure of an electronic component for a tire according to claim 5, wherein the heat-insulating material is formed of any of resin foam, organic fibers and inorganic fibers.

7. (Currently amended) The installation structure of an electronic component for a tire according to ~~any of claims 3 to 6~~ claim 3, wherein the pedestal is formed of resin of which continuous duty is allowed at temperatures of no less than 80°C.

8. (Currently amended) The installation structure of an electronic component for a tire according to ~~any of claims 3 to 7~~ claim 3, wherein a patch which can be bonded to the installation position is integrated with the pedestal.

9. (Original) The installation structure of an electronic component for a tire according to claim 8, wherein through holes are provided in the patch at positions corresponding to the supporting parts of the pedestal, and the pedestal is held by the patch while inserting the supporting parts into the through holes.